

IN THE ABSTRACT:

Please amend the abstract as follows:

Abstract of the Disclosure

A method of testing wire-bond connections between a bonding wire and a substrate surface. The wire-bond connections are produced by a bonding head with a bonding tool and a wire clamp associated with the bonding tool under pressure and the action of ultrasound and/or heat. After the bonded connection has been created, the bonding head or the bonding tool is raised a short distance away from the bonding site, the bonding wire is firmly gripped by the wire clamp and the bonding head. The wire clamp with bonding wire gripped therein is raised for a second distance, during which process the tensile force acting on the bonding wire is detected.

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